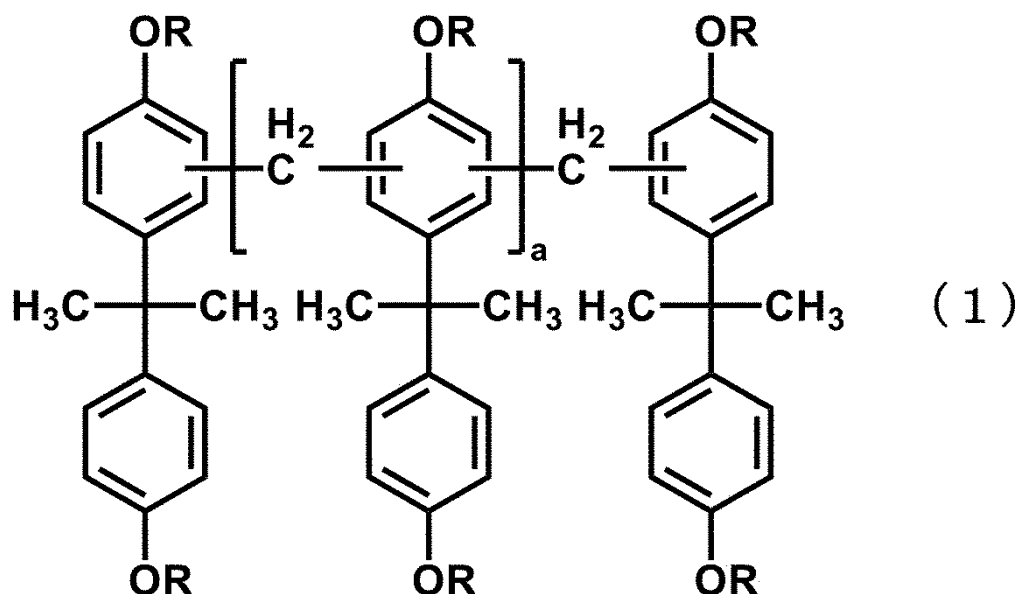


ABSTRACT

The present invention is a negative-type photosensitive resin composition that contains (A) an epoxy resin, (B) a compound that has a phenolic hydroxyl group, and (C) a photo-cationic polymerization initiator. At least 30 mass% of the (A) epoxy resin is an epoxy resin (A-1) represented by formula (1) (in which the Rs each independently represent a glycidyl group or a hydrogen atom, provided that at least two of the Rs are glycidyl groups, and a represents the average number of repeating units and is a real number from 0 to 30, inclusive). The (B) compound that has a phenolic hydroxyl group and the (C) photo-cationic polymerization initiator have specific structures.



[No figure]